

a.) Amendments to the Claims

Claims 1-47 (Cancelled).

48. (Currently Amended) A maleimide composition comprising

(a) a liquid maleimide; and

(b) a peroxide cure initiator,

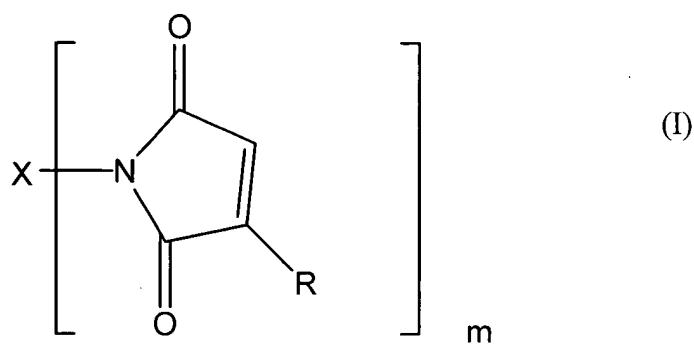
wherein said maleimide composition, a maleimide-containing curable component which when dispensed between a 300 x 300 mil silica die and a Ag coated lead frame as a 1 mil bondline and cured for 1 minute at a temperature of about 200°C, demonstrates an initial adhesion value of at least 115 lbs ~~and a post pressure cooker adhesion of at least 83 lbs.~~

Claim 49 (Cancelled).

50. (Previously Presented) The composition of Claim 48, substantially free of inert diluent.

51. (Previously Presented) A composition comprising

(a) a liquid maleimide comprising:



wherein:

each R is independently hydrogen or lower alkyl,

-X- is a branched chain alkyl or alkylene species having at least 12 carbon atoms, and

m is 1, 2 or 3;

(b) a peroxide cure initiator.

Claims 52-53 (Cancelled).

54. (Previously Presented) An assembly comprising a first article permanently adhered to a second article by a cured aliquot of the composition of Claim 48.

55. (Previously Presented) An assembly comprising a first article permanently adhered to a second article by a cured aliquot of the composition of Claim 51.

56. (Previously Presented) The composition of Claim 48, further comprising a filler.

57. (Previously Presented) The composition of Claim 51, further comprising a filler.

Claim 58 (Cancelled)

59. (Previously Presented) The composition of Claim 51, substantially free of inert diluent.

60. (Previously Presented) The composition of Claim 54 wherein the first article is a silicon die.

61. (Previously Presented) The composition of Claim 55 wherein the first article is a silicon die.